

PCN Number:	20151211002		PCN Date:	12/16/2015																									
Title:	Addition of UMC-F8E for select ASWITCH niche devices and RFAB for select Hammer niche devices																												
Customer Contact:	PCN Manager		Dept:	Quality Services																									
Proposed 1st Ship Date:	03/16/2016		Estimated Sample Availability:	Date provided at sample request.																									
Change Type:																													
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																								
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																								
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																								
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																								
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																								
		<input type="checkbox"/>	Part number change																										
PCN Details																													
Description of Change:																													
This change notification is to announce the addition of UMC-F8E for select ASWITCH niche devices and RFAB for select Hammer niche devices.																													
<table border="1"> <thead> <tr> <th colspan="3">Current Sites</th> <th colspan="3">Additional Sites</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>CFAB</td> <td>LBC7</td> <td>200mm</td> <td>UMC-F8E</td> <td>LBC7</td> <td>200mm</td> </tr> <tr> <td>DP1DM5</td> <td>LBC7</td> <td>200 mm</td> <td>RFAB</td> <td>LBC7</td> <td>300 mm</td> </tr> </tbody> </table>						Current Sites			Additional Sites			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	CFAB	LBC7	200mm	UMC-F8E	LBC7	200mm	DP1DM5	LBC7	200 mm	RFAB	LBC7	300 mm
Current Sites			Additional Sites																										
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																								
CFAB	LBC7	200mm	UMC-F8E	LBC7	200mm																								
DP1DM5	LBC7	200 mm	RFAB	LBC7	300 mm																								
Devices are grouped in the following manner:																													
Group 1: Devices currently at CFAB adding UMC-F8E																													
Group 2: Devices currently at DP1DM5 adding RFAB																													
Qual details are provided in the Qual Data Section.																													
Reason for Change:																													
Continuity of Supply																													
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																													
None																													
Changes to product identification resulting from this PCN:																													
Current																													
Chip Sites	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																										
CFAB	CU3	CHN	Chengdu																										
DP1DM5	DM5	USA	Richardson																										
New																													
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																										
UMC-F8E	U8E	TWN	Hsinchu																										
RFAB	RFB	USA	Richardson																										

Sample product shipping label (not actual product label)

 MADE IN: Malaysia 2DC: 20: MSL 2 / 260C / 1 YEAR SEAL DT MSL 1 / 235C / UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (20L) CS0: SHF (21L) CC0: USA (22L) AS0: MLA (23L) AC0: MYS
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Product Affected:

Group 1: Devices currently at CFAB adding UMC-F8E			
TPS22959DNYR	TPS22961DNYR	TPS22962DNYR	TPS22969DNYR
TPS22959DNYT	TPS22961DNYT	TPS22962DNYT	TPS22969DNYT
Group 2: Devices currently at DP1DM5 adding RFAB			
SNC7007PAP	SNC7007PAPR		

QUALIFICATION DATA

TPS22961DNYR: New Fab location (UMC) for NexFET (GJN13305A0), A-T site is UTAC

Approve Date 10/29/2015

Product Attributes

Attributes	Qual Device: TPS22961DNYR	QBS Product Reference: TPS22961DNYR	QBS Process Reference: BQ24730RGF	QBS Process Reference: CD3230A0YFF	QBS Process Reference: CD3230A0YFF
Assembly Site	UTAC -THAILAND	UTAC -THAILAND	MLA	TI-CLARK	JCAP
Package Family	VSON	VSON	QFN	WCSP (BOP-COA)	WCSP (BOP-COA)
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	-	-
Wafer Fab Supplier	MIHO8, UMC	CFAB, MIHO8	MIHO8	MIHO8	MIHO8
Wafer Process	LBC7, NU35LN	LBC7, NU35LN	LBC7	LBC7	LBC7

- QBS: Qual By Similarity
- Qual Device TPS22961DNYR is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS22961DNYR	QBS Product Reference: TPS22961DNYR	QBS Process Reference: BQ24730RGF	QBS Process Reference: CD3230A0YFF	QBS Process Reference: CD3230A0YFF
AC	Autoclave 121C	96 Hours	-	3/231/0	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	1/77/0	2/154/0
HBM	ESD - HBM	3000 V	1/3/2000	-	-	-	-
CDM	ESD - CDM	1500 V	1/3/2000	1/3/2000	3/9/2000	2/6/2000	1/3/2000
HTOL	Life Test, 125C	1000 Hours	-	-	-	1/77/0	1/77/0
HTOL	Life Test, 155C	240 Hours	-	3/231/0	3/231/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	1/77/0	3/230/0	-	1/77/0	1/77/0
LU	Latch-up	(per JESD78)	1/6/2000	1/6/2000	3/15/2000	2/24/2000	1/12/2000
PD	Physical Dimensions	--	-	3/15/2000	-	3/15/2000	3/15/2000
SBS	Bump-shear	Bumps	-	-	-	3/15/2000	3/150/0
SD	Surface Mount Solderability	Pb Free	-	3/75/0	-	-	-
TC	Temperature Cycle -55/125C	700 Cycles	-	-	-	1/77/0	2/154/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	3/231/0	3/231/0	-	-
TS	Thermal Shock, -65/150C	500 Cycles	-	-	3/231/0	-	-
WBP	Bond Pull	Wires	1/76/0	3/228/0	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report

RFAB Qualification - 300mm LBC7 Process Technology Approve Date 10/06/2010

Product Attributes

Attributes	Qual Device: TPS51217DSC
Assembly Site	CLARK-AT
Package Family	WSON
Flammability Rating	UL 94 V-0
Wafer Fab Supplier	RFAB
Wafer Fab Process	LBC7

- QBS: Qual By Similarity
- Qual Device TPS51217DSC is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS51217DSC
AC	Autoclave 121C	96 Hours	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/60/0
HAST	Biased HAST 130C/85%RH	96 Hours	3/231/0
HTOL	Life Test, 135C	635 Hours	3/231/0
HTSL	High Temp Storage Bake, 170C	420 Hours	3/231/0
TC	Temperature Cycle -65/150C	500 Cycles	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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